



# TSV991-TSV992-TSV994

Rail-to-rail input/output 20MHz GBP operational amplifiers

## Features

- Low input offset voltage: 1.5mV max
- Rail-to-rail input and output
- Wide bandwidth 20MHz, stable for gain  $\geq 3$
- Low power consumption: 1.1mA maximum
- High output current: 35mA
- Operating from 2.5V to 5.5V
- Low input bias current, 1pA typ
- ESD internal protection  $\geq 5kV$
- Latch-up immunity

## Description

The TSV991/2/4 family of single, dual & quad operational amplifiers offers low voltage operation and rail-to-rail input and output.

This family features an excellent speed/power consumption ratio, offering a 20MHz gain-bandwidth, stable for gain above 3 (100pF capacitive load), while consuming only 1.1mA max at 5V supply voltage. It also features an ultra-low input bias current.

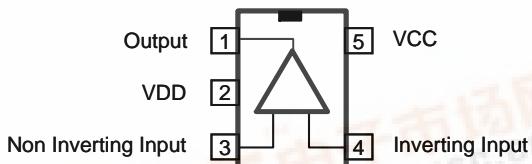
These characteristics make the TSV991/2/4 family ideal for sensor interfaces, battery-supplied and portable applications, as well as active filtering.

## Applications

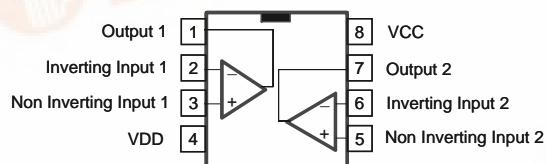
- Battery-powered applications
- Portable devices
- Signal conditioning
- Active filtering
- Medical instrumentation

### Pin connections (top view)

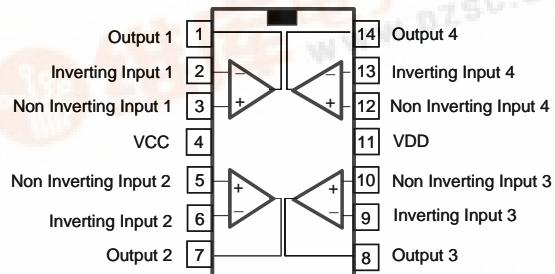
#### SOT23-5



#### MSO-8, SO-8



#### SO-14, TSSOP14



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# 1 Absolute maximum ratings & operating conditions

**Table 1. Absolute maximum ratings (AMR)**

Symbol	Parameter	Value	Unit
$V_{CC}$	Supply voltage <sup>(1)</sup>	6	V
$V_{id}$	Differential input voltage <sup>(2)</sup>	$\pm V_{CC}$	V
$V_{in}$	Input voltage <sup>(3)</sup>	$V_{DD}-0.2$ to $V_{CC}+0.2$	V
$T_{stg}$	Storage temperature	-65 to +150	°C
$R_{thja}$	Thermal resistance junction to ambient <sup>(4) (5)</sup>		°C/W
	SOT23-5	250	
	SO-8	125	
	MiniSO-8	190	
	SO-14	103	
	TSSOP14	100	
$R_{thjc}$	Thermal resistance junction to case		°C/W
	SOT23-5	81	
	SO-8	40	
	MiniSO8	39	
	SO14	31	
	TSSOP14	32	
$T_j$	Maximum junction temperature	150	°C
ESD	HBM: human body model <sup>(6)</sup>	5	kV
	MM: machine model <sup>(7)</sup>	400	V
	CDM: charged device model <sup>(8)</sup>		
	SOT23-5, SO-8, MSO8, SO14	1500	V
	TSSOP14	750	
	Latch-up immunity	200	mA

1. Value with respect to  $V_{DD}$  pin.
2. Differential voltages are the non-inverting input terminal with respect to the inverting input terminal.
3.  $V_{CC}-V_{in}$  must not exceed 6V.
4. Short-circuits can cause excessive heating and destructive dissipation.
5.  $R_{th}$  are typical values.
6. Human body model: 100pF discharged through a 1.5kΩ resistor between two pins of the device, done for all couples of pin combinations with other pins floating.
7. Machine model: 200pF is charged to the specified voltage, then discharged directly between two pins of the device with no external series resistor (internal resistor  $< 5\Omega$ ), done for all couples of pin combinations with other pins floating.
8. Charged device model: all pins plus package are charged together to the specified voltage and then discharged directly to the ground.

**Table 2. Operating conditions**

Symbol	Parameter	Value	Unit
$V_{CC}$	Supply voltage	2.5 to 5.5	V
$V_{icm}$	Common mode input voltage range	$V_{DD} -0.1$ to $V_{CC} +0.1$	V
$T_{oper}$	Operating free air temperature range	-40 to +125	°C

## 2 Electrical characteristics

**Table 3.** Electrical characteristics at  $V_{CC} = +2.5V$ ,  $V_{DD} = 0V$ ,  $V_{icm} = V_{CC}/2$ ,  $T_{amb} = 25^\circ C$ ,  $R_L$  connected to  $V_{CC}/2$  (unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>DC performance</b>						
$V_{io}$	Offset voltage TSV99x		-	0.1	4.5	mV
		$T_{min} < T_{op} < T_{max}$	-	-	7.5	
	TSV99xA		-	-	1.5	
		$T_{min} < T_{op} < T_{max}$	-	-	3	
$DV_{io}$	Input offset voltage drift		-	2	-	$\mu V/^\circ C$
$I_{io}$	Input offset current <sup>(1)</sup> ( $V_{out} = V_{CC}/2$ )		-	1	10	pA
$I_{ib}$	Input bias current <sup>(1)</sup> ( $V_{out} = V_{CC}/2$ )		-	1	10	pA
CMR	Common mode rejection ratio $20 \log (\Delta V_{ic}/\Delta V_{io})$	0V to 2.5V, $V_{out} = 1.25V$	58	75	-	dB
$A_{vd}$	Large signal voltage gain	$R_L = 10k\Omega$ $V_{out} = 0.5V$ to $2V$	80	89	-	dB
$V_{CC}-V_{OH}$	High level output voltage	$R_L = 10k\Omega$ $R_L = 600\Omega$		15 45	40 150	mV
$V_{OL}$	Low level output voltage	$R_L = 10k\Omega$ $R_L = 600\Omega$	-	15 45	40 150	mV
$I_{out}$	$I_{sink}$	$V_o = 2.5V$	18	32	-	mA
		$T_{min} < T_{amb} < T_{max}$	16	-	-	
	$I_{source}$	$V_o = 0V$	18	35	-	
		$T_{min} < T_{amb} < T_{max}$	16	-	-	
$I_{CC}$	Supply current (per operator)	No load, $V_{out}=V_{CC}/2$	-	0.78	1.1	mA
		$T_{min} < T_{op} < T_{max}$	-	-	1.1	
<b>AC performance</b>						
GBP	Gain bandwidth product	$R_L = 2k\Omega$ , $C_L = 100pF$ , $f = 100kHz$	-	20	-	MHz
$\phi_m$	Phase margin	$R_L = 2k\Omega$ , $C_L = 100pF$ , $G=5$ , $f=100kHz$	-	60	-	Degrees
$G_m$	Gain margin	$R_L = 2k\Omega$ , $C_L = 100pF$ , $\phi_m=40^\circ$	-	2.5	-	dB
SR	Slew rate	$R_L = 2k\Omega$ , $C_L = 100pF$	-	10	-	V/ $\mu s$
$e_n$	Equivalent input noise voltage	$f=10kHz$	-	21	-	$\frac{nV}{\sqrt{Hz}}$
THD+ $e_n$	Total harmonic distortion	$G=1$ , $f=1kHz$ , $R_L=2k\Omega$ , $BW=22kHz$ , $V_{icm}=(V_{cc}+1)/2$ , $V_{out}=1.1V_{pp}$	-	0.0017	-	%

1. Guaranteed by design.

## Electrical characteristics

TSV991-TSV992-TSV994

**Table 4. Electrical characteristics at  $V_{CC} = +3.3V$ ,  $V_{DD} = 0V$ ,  $V_{icm} = V_{CC}/2$ ,  $T_{amb} = 25^\circ C$ ,  $R_L$  connected to  $V_{CC}/2$  (unless otherwise specified)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>DC performance</b>						
$V_{io}$	Offset voltage TSV99x		-	0.1	4.5	mV
		$T_{min} < T_{op} < T_{max}$	-	-	7.5	
	TSV99xA		-	-	1.5	
		$T_{min} < T_{op} < T_{max}$	-	-	3	
$DV_{io}$	Input offset voltage drift		-	2	-	$\mu V/^\circ C$
$I_{io}$	Input offset current <sup>(1)</sup>		-	1	10	pA
$I_{ib}$	Input bias current <sup>(1)</sup>		-	1	10	pA
CMR	Common mode rejection ratio $20 \log (\Delta V_{ic}/\Delta V_{io})$	0V to 3.3V, $V_{out} = 1.65V$	60	78	-	dB
$A_{vd}$	Large signal voltage gain	$R_L=10k\Omega$ , $V_{out}=0.5V$ to 2.8V	80	90	-	dB
$V_{CC}-V_{OH}$	High level output voltage	$R_L = 10k\Omega$ $R_L = 600\Omega$		15 45	40 150	mV
$V_{OL}$	Low level output voltage	$R_L = 10k\Omega$ $R_L = 600\Omega$	-	15 45	40 150	mV
$I_{out}$	$I_{sink}$	$V_o = 3.3V$	18	32	-	mA
		$T_{min} < T_{amb} < T_{max}$	16	-	-	
	$I_{source}$	$V_o = 0V$	18	35	-	
		$T_{min} < T_{amb} < T_{max}$	16	-	-	
$I_{CC}$	Supply current (per operator)	No load, $V_{out}=V_{CC}/2$	-	0.8	1.1	mA
		$T_{min} < T_{op} < T_{max}$	-	-	1.1	
<b>AC performance</b>						
GBP	Gain bandwidth product	$R_L = 2k\Omega$ , $C_L = 100pF$ , $f = 100kHz$	-	20	-	MHz
$\phi_m$	Phase margin	$R_L = 2k\Omega$ , $C_L = 100pF$ , $G=5$	-	60	-	Degrees
$G_m$	Gain margin	$R_L = 2k\Omega$ , $C_L = 100pF$ , $f = 100kHz$ , $\phi_m=40^\circ$	-	2.5	-	dB
SR	Slew rate	$R_L = 2k\Omega$ , $C_L = 100pF$ , $f = 100kHz$	-	10	-	V/ $\mu$ s
$e_n$	Equivalent input noise voltage	$f=10kHz$	-	21	-	$\frac{nV}{\sqrt{Hz}}$
THD+ $e_n$	Total harmonic distortion	$G=1$ , $f=1kHz$ , $R_L=2k\Omega$ , $BW=22kHz$ , $V_{icm}=(V_{cc}+1)/2$ , $V_{out}=1.9V_{pp}$	-	0.001	-	%

1. Guaranteed by design.

**Table 5. Electrical characteristics at  $V_{CC} = +5V$ ,  $V_{DD} = 0V$ ,  $V_{icm} = V_{CC}/2$ ,  $T_{amb} = 25^\circ C$ ,  $R_L$  connected to  $V_{CC}/2$  (unless otherwise specified)**

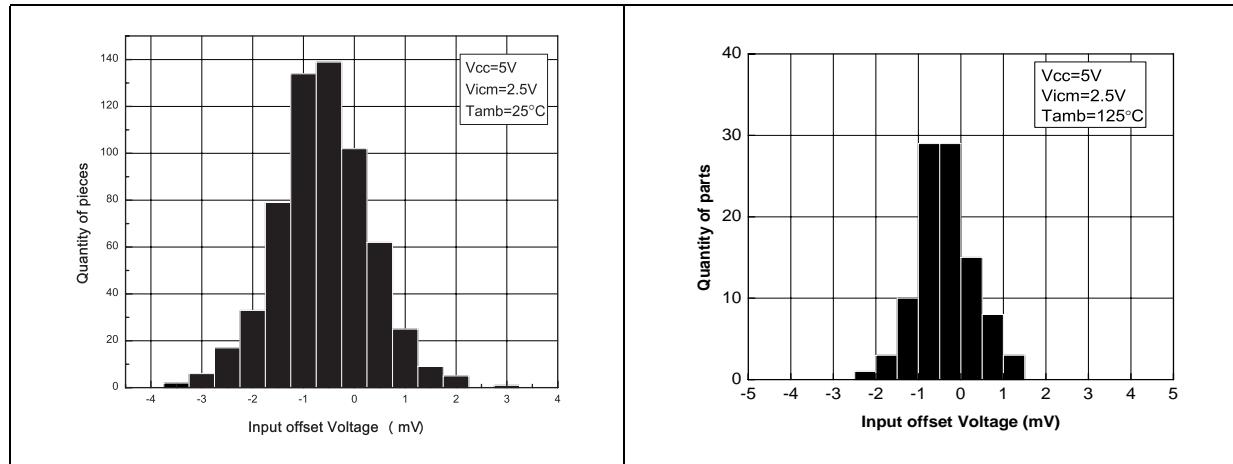
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>DC performance</b>						
$V_{io}$	Offset voltage TSV99x		-	0.1	4.5	mV
		$T_{min} < T_{op} < T_{max}$	-	-	7.5	
	TSV99xA		-	-	1.5	
		$T_{min} < T_{op} < T_{max}$	-	-	3	
$DV_{io}$	Input offset voltage drift		-	2	-	$\mu V/^\circ C$
$I_{io}$	Input offset current <sup>(1)</sup>		-	1	10	pA
$I_{ib}$	Input bias current <sup>(1)</sup>		-	1	10	pA
CMR	Common mode rejection ratio $20 \log (\Delta V_{ic}/\Delta V_{io})$	0V to 5V, $V_{out} = 2.5V$	62	82	-	dB
SVR	Supply voltage rejection ratio $20 \log (\Delta V_{cc}/\Delta V_{io})$	$V_{CC} = 2.5$ to 5V	70	86	-	dB
$A_{vd}$	Large signal voltage gain	$R_L=10k\Omega$ $V_{out}=0.5V$ to 4.5V	80	91	-	dB
$V_{CC}-V_{OH}$	High level output voltage	$R_L = 10k\Omega$ $R_L = 600\Omega$		15 45	40 150	mV
$V_{OL}$	Low level output voltage	$R_L = 10k\Omega$ $R_L = 600\Omega$	-	15 45	40 150	mV
$I_{out}$	$I_{sink}$	$V_o = 5V$	18	32	-	mA
		$T_{min} < T_{amb} < T_{max}$	16	-	-	
	$I_{source}$	$V_o = 0V$	18	35	-	
		$T_{min} < T_{amb} < T_{max}$	16	-	-	
$I_{CC}$	Supply current (per operator)	No load, $V_{out}=2.5V$	-	0.82	1.1	mA
		$T_{min} < T_{op} < T_{max}$	-	-	1.1	
<b>AC performance</b>						
GBP	Gain bandwidth product	$R_L = 2k\Omega$ $C_L = 100pF$ , $f = 100kHz$	-	20	-	MHz
$\phi_m$	Phase margin	$R_L = 2k\Omega$ , $C_L = 100pF$ , $G=5$	-	60	-	Degrees
$G_m$	Gain margin	$R_L = 2k\Omega$ , $C_L=100pF$ , $\phi_m=40^\circ$	-	2.5	-	dB
SR	Slew rate	$R_L = 2k\Omega$ $C_L = 100pF$	-	10	-	V/ $\mu s$
$e_n$	Equivalent input noise voltage	$f=10kHz$	-	21	-	$\frac{nV}{\sqrt{Hz}}$
THD+ $e_n$	Total harmonic distortion	$G=1$ , $f=1kHz$ , $R_L=2k\Omega$ , $BW=22kHz$ , $Vicm=(V_{cc}+1)/2$ , $Vout=3.6Vpp$	-	0.0007	-	%

1. Guaranteed by design.

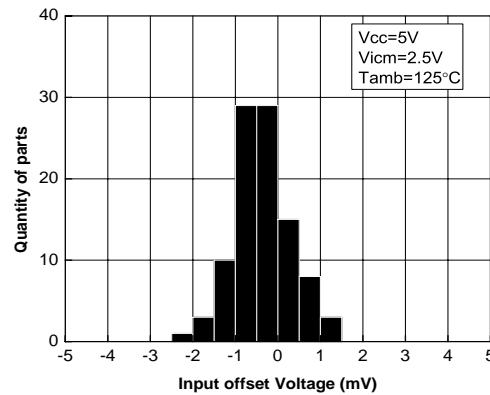
## Electrical characteristics

TSV991-TSV992-TSV994

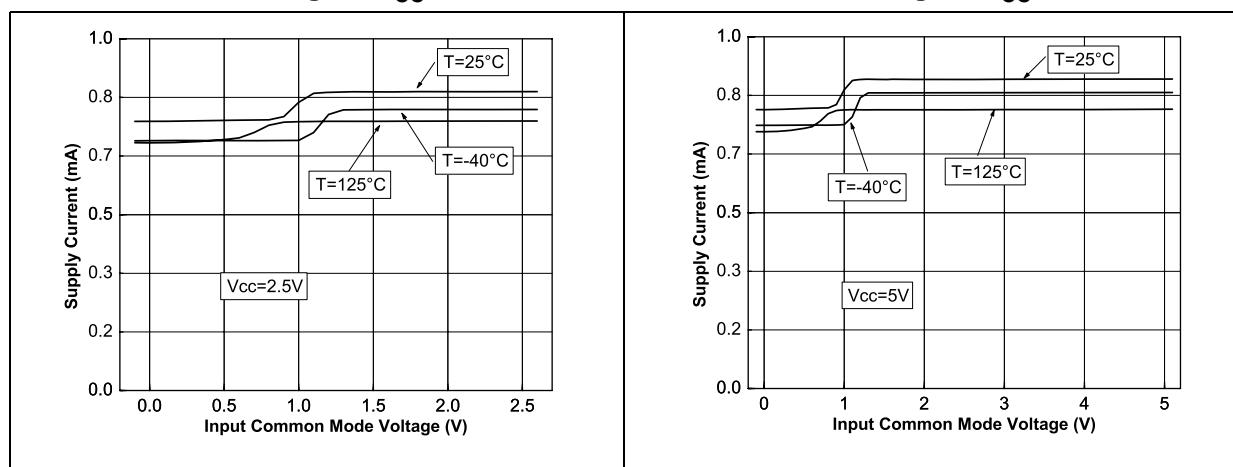
**Figure 1. Input offset voltage distribution at T=25°C**



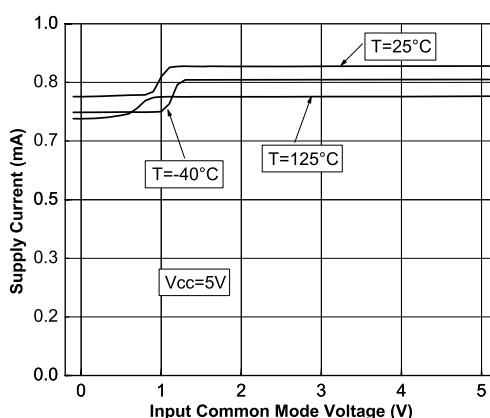
**Figure 2. Input offset voltage distribution at T=125°C**



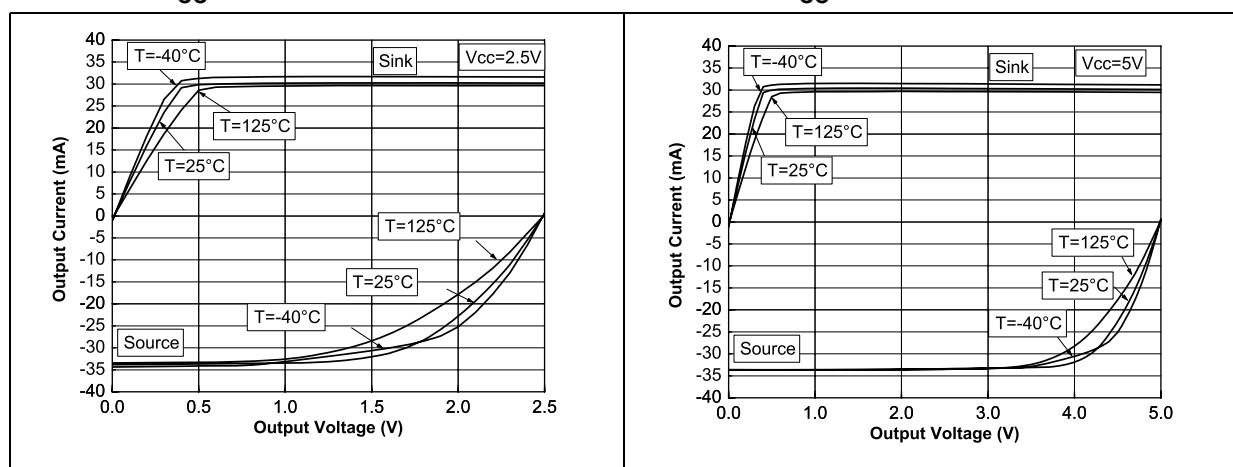
**Figure 3. Supply current vs. input common mode voltage at  $V_{\text{CC}}=2.5\text{V}$**



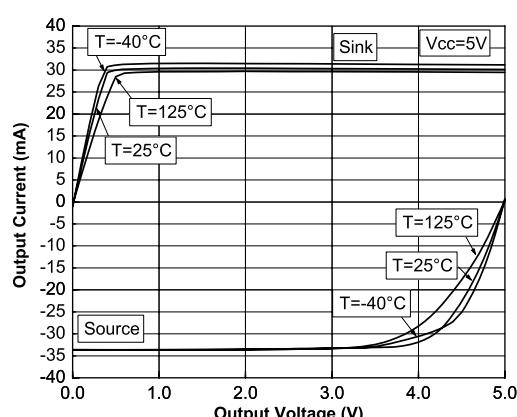
**Figure 4. Supply current vs. input common mode voltage at  $V_{\text{CC}}=5\text{V}$**



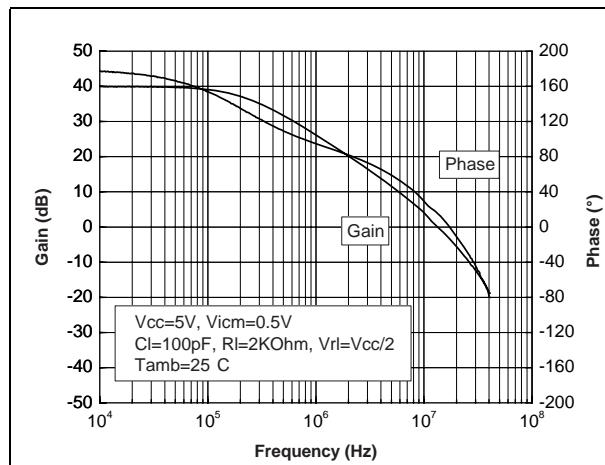
**Figure 5. Output current vs. output voltage at  $V_{\text{CC}}=2.5\text{V}$**



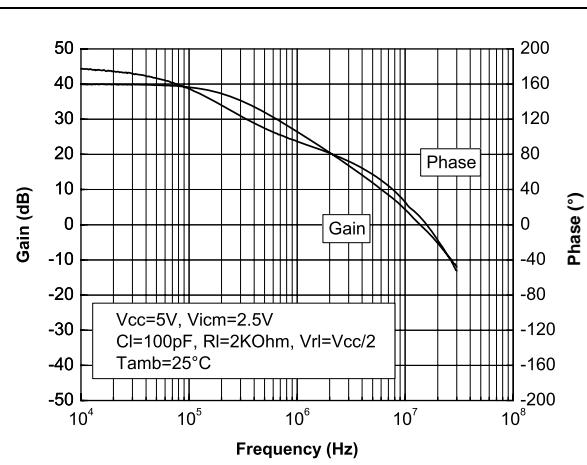
**Figure 6. Output current vs. output voltage at  $V_{\text{CC}}=5\text{V}$**



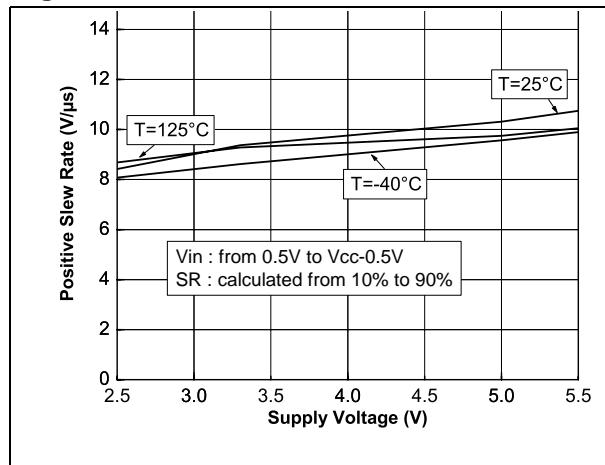
**Figure 7. Voltage gain and phase vs frequency at  $V_{CC}=5V$  and  $V_{icm}=0.5V$**



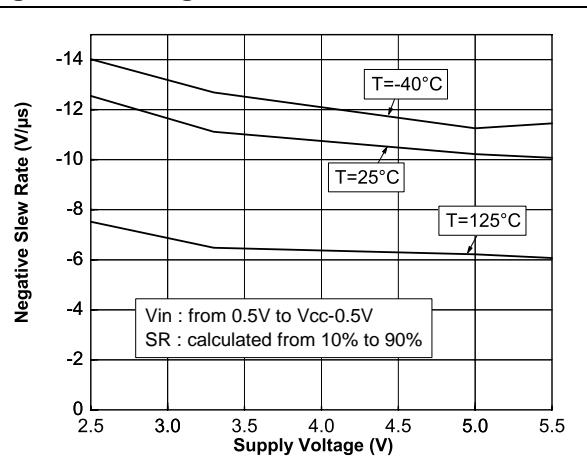
**Figure 8. Voltage gain and phase vs frequency at  $V_{CC}=5V$  and  $V_{icm}=2.5V$**



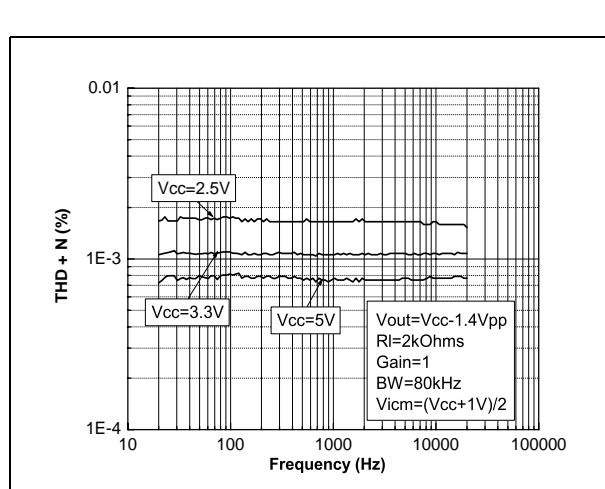
**Figure 9. Positive slew rate**



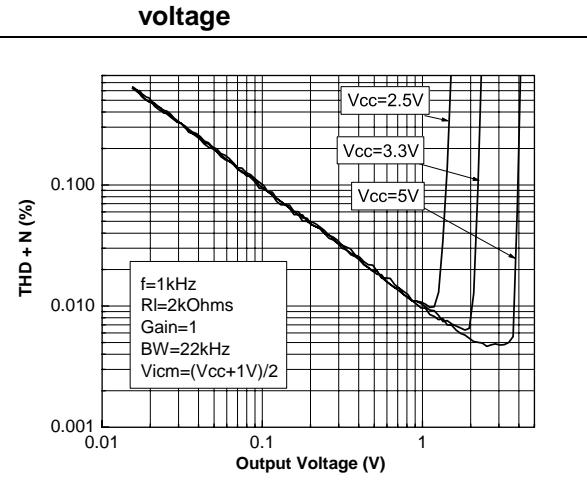
**Figure 10. Negative slew rate**

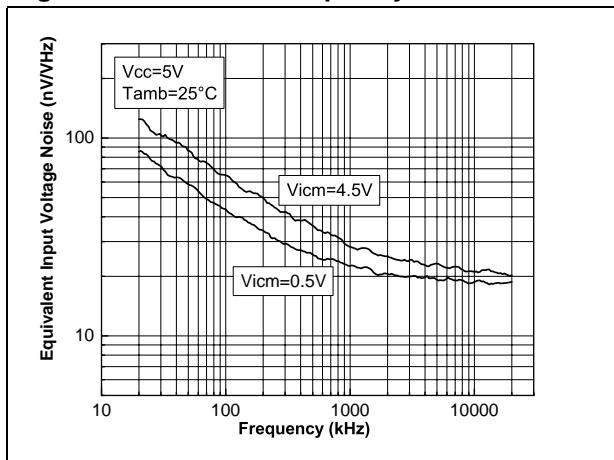


**Figure 11. Distortion + noise vs. frequency**



**Figure 12. Distortion + noise vs. output voltage**



**Figure 13. Noise vs. frequency**

### 3 Package information

In order to meet environmental requirements, STMicroelectronics offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an STMicroelectronics trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com).

**Figure 14. SOT23-5 package**

Ref.	Dimensions					
	Millimeters			Mils		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.90		1.45	35.4		57.1
A1	0.00		0.15	0.00		5.9
A2	0.90		1.30	35.4		51.2
b	0.35		0.50	13.7		19.7
C	0.09		0.20	3.5		7.8
D	2.80		3.00	110.2		118.1
E	2.60		3.00	102.3		118.1
E1	1.50		1.75	59.0		68.8
e		0.95			37.4	
e1		1.9			74.8	
L	0.35		0.55	13.7		21.6

The diagram illustrates the physical dimensions of the SOT23-5 package. The left side shows a front view with dimensions A (total width), C (width of the lead), A1 (lead thickness), A2 (lead height), and L (lead length). The right side shows a top view with dimensions e1 (width of the lead frame), e (width of the lead frame between leads), b (lead pitch), D (total length), E (total height), and E1 (height of the lead frame). The package is shown in a lead-free ECOPACK version.

**Figure 15. MiniSO-8 package**

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.1			0.043
A1	0.05	0.10	0.15	0.002	0.004	0.006
A2	0.78	0.86	0.94	0.031	0.034	0.037
b	0.25	0.33	0.40	0.010	0.013	0.016
c	0.13	0.18	0.23	0.005	0.007	0.009
D	2.90	3.00	3.10	0.114	0.118	0.122
E	4.75	4.90	5.05	0.187	0.193	0.199
E1	2.90	3.00	3.10	0.114	0.118	0.122
e		0.65			0.026	
K	0°		6°	0°		6°
L	0.40	0.55	0.70	0.016	0.022	0.028
L1			0.10			0.04

The figure contains three technical drawings of the MiniSO-8 package. The top drawing shows a side cross-section with dimensions: E1 (height), c (width), k (lead thickness), L (lead height), L1 (lead lead-in height), and GAGE PLANE. The middle drawing shows a top-down view with dimensions A, A1, A2, b, D, E, and 5, 4, 1 pins. The bottom drawing shows a pin identification diagram with a dot at Pin 1.

**Figure 16. SO-8 package**

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	1.35		1.75	0.053		0.069
A1	0.10		0.25	0.04		0.010
A2	1.10		1.65	0.043		0.065
B	0.33		0.51	0.013		0.020
C	0.19		0.25	0.007		0.010
D	4.80		5.00	0.189		0.197
E	3.80		4.00	0.150		0.157
e		1.27			0.050	
H	5.80		6.20	0.228		0.244
h	0.25		0.50	0.010		0.020
L	0.40		1.27	0.016		0.050
k	8° (max.)					
ddd			0.1			0.04

The figure contains three technical drawings of an SO-8 package. The top drawing is a top-down view showing the footprint and lead positions, with dimensions D, H, e, A, A1, and B. The middle drawing is a side view showing the profile and lead angle hx45°. The bottom drawing is a cross-sectional view showing the lead length L, lead angle k, seating plane C, and gage plane at 0.25 mm. Pin numbers 1 through 8 are also indicated on the top view.

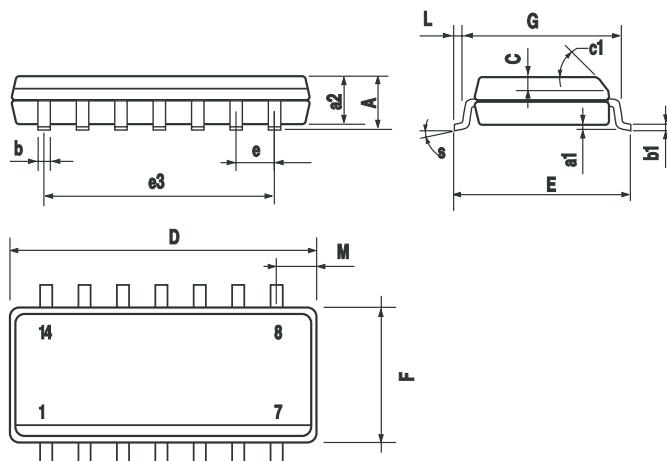
Figure 17. TSSOP14 package

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.2			0.047
A1	0.05		0.15	0.002	0.004	0.006
A2	0.8	1	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.0089
D	4.9	5	5.1	0.193	0.197	0.201
E	6.2	6.4	6.6	0.244	0.252	0.260
E1	4.3	4.4	4.48	0.169	0.173	0.176
e		0.65 BSC			0.0256 BSC	
K	0°		8°	0°		8°
L1	0.45	0.60	0.75	0.018	0.024	0.030

The technical drawing illustrates the physical dimensions of the TSSOP14 package. It shows a top-down view of the package with pins at the bottom. Key dimensions labeled include A (total height), A1 (lead thickness), A2 (lead spacing), b (width of the lead frame), c (pitch between leads), D (total width of the chip area), E (total length of the chip area), E1 (length of the chip area), and K (angle of the lead). A callout labeled 'PIN 1 IDENTIFICATION' points to the first pin on the left side, which is marked with a small circle and the number '1'.

**Figure 18. SO-14 package**

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.75			0.068
a1	0.1		0.2	0.003		0.007
a2			1.65			0.064
b	0.35		0.46	0.013		0.018
b1	0.19		0.25	0.007		0.010
C		0.5			0.019	
c1	45° (typ.)					
D	8.55		8.75	0.336		0.344
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		7.62			0.300	
F	3.8		4.0	0.149		0.157
G	4.6		5.3	0.181		0.208
L	0.5		1.27	0.019		0.050
M			0.68			0.026
S	8° (max.)					

The technical drawing illustrates the SO-14 package with three views: a top view showing the 14 pins numbered 1 through 14, a side view showing the profile with dimensions L, G, c1, a1, b1, and s, and a front view showing the lead spacing e3 and other side dimensions.

## 4 Ordering information

Part number	Temperature range	Package	Packing	Marking	
TSV991ILT	-40°C to +125°C	SOT23-5	Tape & reel	K130	
TSV991AILT				K129	
TSV992IST		MiniSO-8		K132	
TSV992AIST				K135	
TSV992ID		SO-8	Tube or tape & reel	V992I	
TSV992IDT				V992AI	
TSV992AID		TSSOP14	Tape & reel	V994I	
TSV992AIDT				V994AI	
TSV994IPT		SO-14	Tube or tape & reel	V994I	
TSV994AIPT				V994AI	
TSV994ID					
TSV994IDT					
TSV994AID					
TSV994AIDT					

## 5 Revision history

Date	Revision	Changes
31-Jul-2006	1	Preliminary data release for product under development.
7-Nov-2006	2	Final version of datasheet.
12-Dec-2006	3	Noise and distortion figures added.

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